

**Features:**

- Non-Isolated. Mounting base as common anode cathode terminal.
- Pressure contact technology with Increased power cycling capability
- Low forward voltage drop

Typical Applications:

- Welding Power Supply.
- Various Dc power supplies.

V_{RRM}	Type & Outline		
	800V	1000V	1200V
1400V	MDx50-14-213F4	MDx50-16-213F4	MDx50-18-213F4
1600V	MDx50-16-213F4	MDx50-18-213F4	
1800V	MDx50-18-213F4		

MDx stands for any type of **MDG, MDY**

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j(°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _c =100°C	150			50	A
I _{F(RMS)}	RMS forward current					78	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			8	mA
I _{FSM}	Surge forward current	V _R =60%V _{RRM} , t=10ms half sine	150			1.4	kA
I ² t	I ² t for fusing coordination					9.8	10 ³ A ² s
V _{FO}	Threshold voltage		150			0.80	V
r _F	Forward slope resistance					4.78	mΩ
V _{FM}	Peak forward voltage	I _{FM} =150A	25			1.60	V
R _{th(j-c)}	Thermal resistance Junction to case	At 180° sine. Single side cooled per chip				0.70	°C/W
R _{th(c-h)}	Thermal resistance case to heatsink	At 180° sine. Single side cooled per chip				0.10	°C/W
F _m	Terminal connection torque(M6)			4.5		6.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T _{vj}	Junction temperature			-40		150	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				280		g
Outline				213F4			

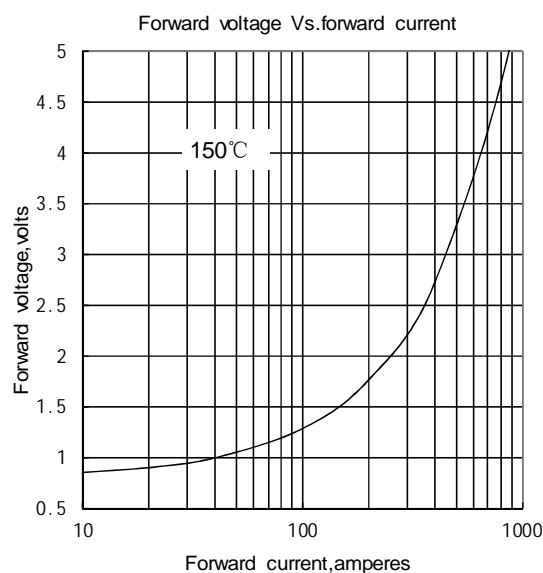


Fig.1

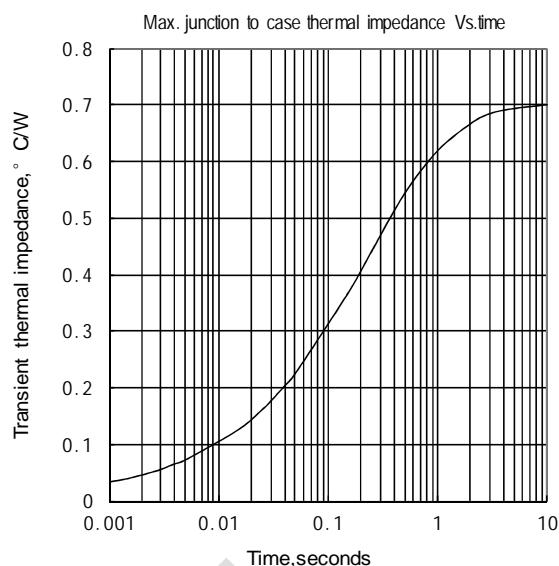


Fig.2

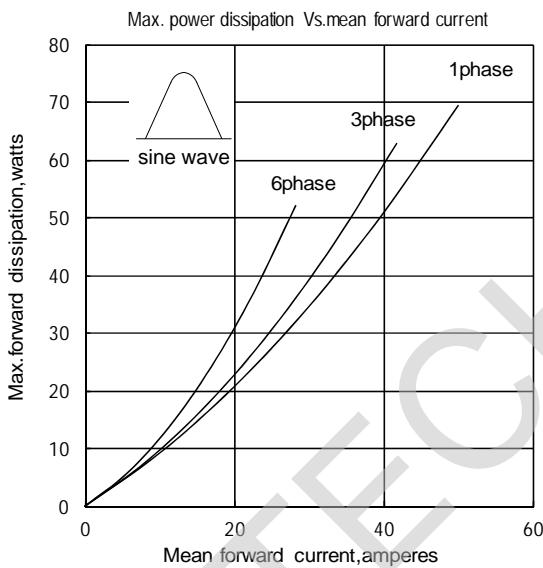


Fig.3

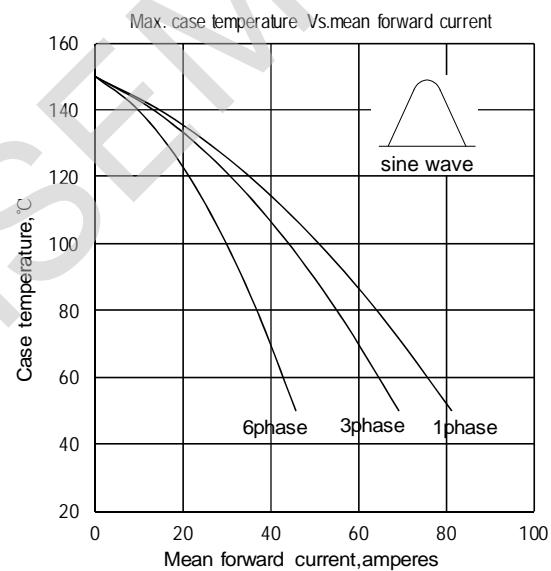


Fig.4

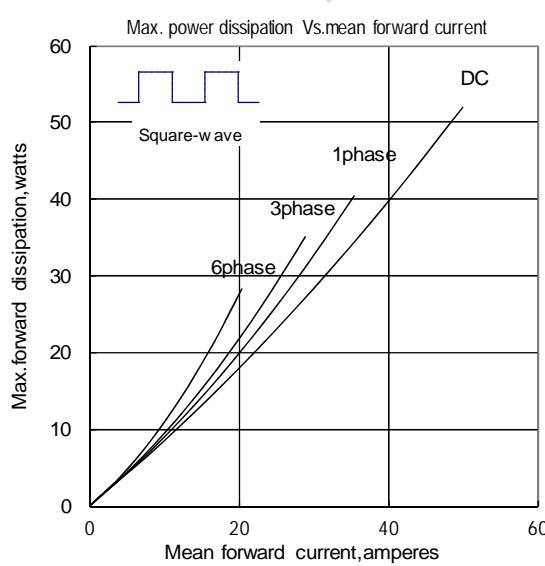


Fig.5

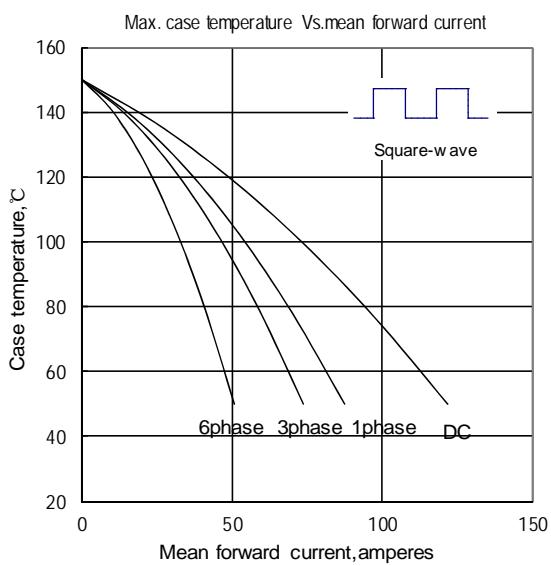


Fig.6

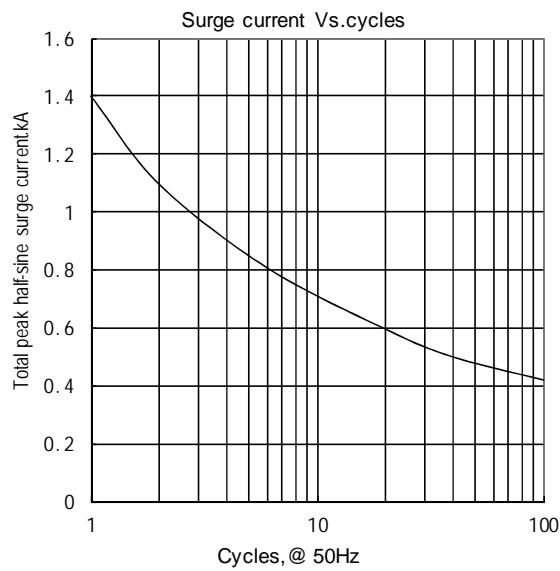


Fig.7

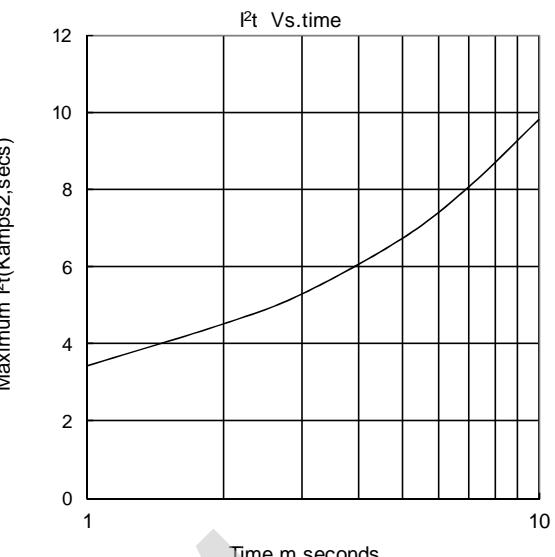
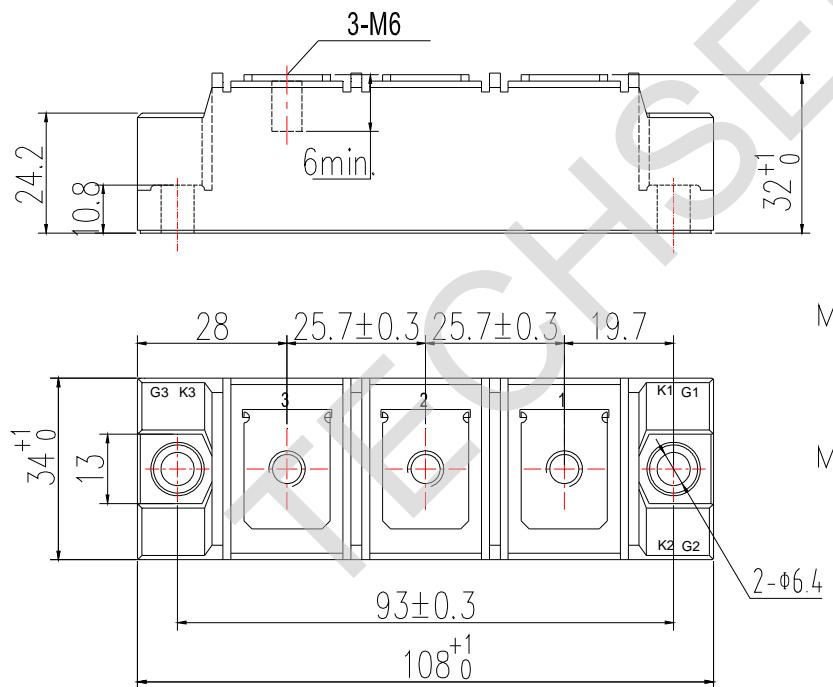
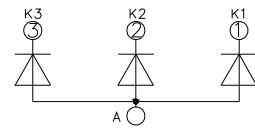


Fig.8

Outline:

Unmarked dimensional tolerance: ±0.5mm

MDG



MDY

